

FAIRCHILD
SEMICONDUCTOR®

February 2005

FDP8880 / FDB8880 N-Channel PowerTrench® MOSFET

30V, 54A, 11.6mΩ

Features

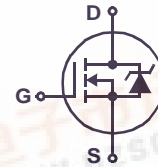
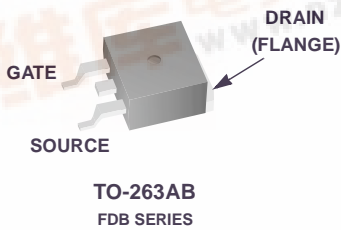
- $r_{DS(ON)} = 14.5m\Omega$ $V_{GS} = 4.5V$, $I_D = 40A$
- $r_{DS(ON)} = 11.6m\Omega$ $V_{GS} = 10V$, $I_D = 40A$
- High performance trench technology for extremely low $r_{DS(ON)}$
- Low gate charge
- High power and current handling capability

Applications

- DC/DC converters

General Description

This N-Channel MOSFET has been designed specifically to improve the overall efficiency of DC/DC converters using either synchronous or conventional switching PWM controllers. It has been optimized for low gate charge, low $r_{DS(ON)}$ and fast switching speed.



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Ratings | Units |
|----------------|---|------------|---------------------|
| V_{DSS} | Drain to Source Voltage | 30 | V |
| V_{GS} | Gate to Source Voltage | ± 20 | V |
| I_D | Drain Current | | |
| | Continuous ($T_C = 25^\circ\text{C}$, $V_{GS} = 10\text{V}$) | 54 | A |
| | Continuous ($T_C = 25^\circ\text{C}$, $V_{GS} = 4.5\text{V}$) | 48 | A |
| | Continuous ($T_{amb} = 25^\circ\text{C}$, $V_{GS} = 10\text{V}$, with $R_{\theta JA} = 43^\circ\text{C/W}$) | 11 | A |
| | Pulsed | Figure 4 | A |
| E_{AS} | Single Pulse Avalanche Energy (Note 1) | 31 | mJ |
| P_D | Power dissipation | 55 | W |
| | Derate above 25°C | 0.37 | W/ $^\circ\text{C}$ |
| T_J, T_{STG} | Operating and Storage Temperature | -55 to 175 | $^\circ\text{C}$ |

Thermal Characteristics

| | | | |
|-----------------|---|------|--------------------|
| $R_{\theta JC}$ | Thermal Resistance Junction to Case TO-220,TO-263 | 2.73 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient TO-220,TO-262 (Note 2) | 62 | $^\circ\text{C/W}$ |
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient TO-263, 1in ² copper pad area | 43 | $^\circ\text{C/W}$ |

Package Marking and Ordering Information

| Device Marking | Device | Package | Reel Size | Tape Width | Quantity |
|----------------|---------------------|----------|-----------|------------|-----------|
| FDP8880 | FDP8880 | TO-220AB | Tube | N/A | 50 units |
| FDB8880 | FDB8880 | TO-263AB | 330mm | 24mm | 800 units |
| FDP8880 | FDP8880_NL (Note 3) | TO-220AB | Tube | N/A | 50 units |
| FDB8880 | FDB8880_NL (Note 3) | TO-263AB | 330mm | 24mm | 800 units |

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

| Symbol | Parameter | Test Conditions | Min | Typ | Max | Units |
|--------|-----------|-----------------|-----|-----|-----|-------|
|--------|-----------|-----------------|-----|-----|-----|-------|

Off Characteristics

| | | | | | | |
|------------|-----------------------------------|--|----|---|-----------|---------------|
| B_{VDSS} | Drain to Source Breakdown Voltage | $I_D = 250\mu\text{A}$, $V_{GS} = 0\text{V}$ | 30 | - | - | V |
| I_{DSS} | Zero Gate Voltage Drain Current | $V_{DS} = 24\text{V}$ | - | - | 1 | μA |
| | | $V_{GS} = 0\text{V}$ $T_C = 150^\circ\text{C}$ | - | - | 250 | |
| I_{GSS} | Gate to Source Leakage Current | $V_{GS} = \pm 20\text{V}$ | - | - | ± 100 | nA |

On Characteristics

| | | | | | | |
|--------------|----------------------------------|---|-----|--------|--------|----------|
| $V_{GS(TH)}$ | Gate to Source Threshold Voltage | $V_{GS} = V_{DS}$, $I_D = 250\mu\text{A}$ | 1.2 | - | 2.5 | V |
| $r_{DS(ON)}$ | Drain to Source On Resistance | $I_D = 40\text{A}$, $V_{GS} = 10\text{V}$ | - | 0.0095 | 0.0116 | Ω |
| | | $I_D = 40\text{A}$, $V_{GS} = 4.5\text{V}$ | - | 0.012 | 0.0145 | |
| | | $I_D = 40\text{A}$, $V_{GS} = 10\text{V}$, $T_J = 175^\circ\text{C}$ | - | 0.015 | 0.019 | |
| | | | | | | |

Dynamic Characteristics

| | | | | | | | |
|--------------|----------------------------------|--|--|------|-----|----------|----|
| C_{ISS} | Input Capacitance | $V_{DS} = 15V, V_{GS} = 0V,$ $f = 1MHz$ | - | 1240 | - | pF | |
| C_{OSS} | Output Capacitance | | - | 255 | - | pF | |
| C_{RSS} | Reverse Transfer Capacitance | | - | 147 | - | pF | |
| R_G | Gate Resistance | $V_{GS} = 0.5V, f = 1MHz$ | - | 2.7 | - | Ω | |
| $Q_{g(TOT)}$ | Total Gate Charge at 10V | $V_{GS} = 0V$ to 10V | $V_{DD} = 15V$ $I_D = 40A$ $I_g = 1.0mA$ | - | 22 | 29 | nC |
| $Q_{g(5)}$ | Total Gate Charge at 5V | $V_{GS} = 0V$ to 5V | | - | 12 | 16 | nC |
| $Q_{g(TH)}$ | Threshold Gate Charge | $V_{GS} = 0V$ to 1V | | - | 1.6 | 2.1 | nC |
| Q_{gs} | Gate to Source Gate Charge | | | - | 3.2 | - | nC |
| Q_{gs2} | Gate Charge Threshold to Plateau | | | - | 2.0 | - | nC |
| Q_{gd} | Gate to Drain "Miller" Charge | | | - | 4.8 | - | nC |

Switching Characteristics ($V_{GS} = 10V$)

| | | | | | | |
|--------------|---------------------|--|---|-----|-----|----|
| t_{ON} | Turn-On Time | $V_{DD} = 15V, I_D = 40A$ $V_{GS} = 10V, R_{GS} = 13.6\Omega$ | - | - | 171 | ns |
| $t_{d(ON)}$ | Turn-On Delay Time | | - | 8 | - | ns |
| t_r | Rise Time | | - | 107 | - | ns |
| $t_{d(OFF)}$ | Turn-Off Delay Time | | - | 47 | - | ns |
| t_f | Fall Time | | - | 51 | - | ns |
| t_{OFF} | Turn-Off Time | | - | - | 147 | ns |

Drain-Source Diode Characteristics

| | | | | | | |
|----------|-------------------------------|---|---|---|------|----|
| V_{SD} | Source to Drain Diode Voltage | $I_{SD} = 40A$ | - | - | 1.25 | V |
| | | $I_{SD} = 3.5A$ | - | - | 1.0 | V |
| t_{rr} | Reverse Recovery Time | $I_{SD} = 40A, di_{SD}/dt = 100A/\mu s$ | - | - | 27 | ns |
| Q_{RR} | Reverse Recovered Charge | $I_{SD} = 40A, di_{SD}/dt = 100A/\mu s$ | - | - | 18 | nC |

Notes:

- Starting $T_J = 25^\circ C, L = 34\mu H, I_{AS} = 43A, V_{dd} = 27V, V_{gs} = 10V.$
- Pulse width = 100s.
- FDP8880_NL / FDB8880_NL is lead free product.
FDP8880_NL / FDB8880_NL marking will appear on the reel label.

Typical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

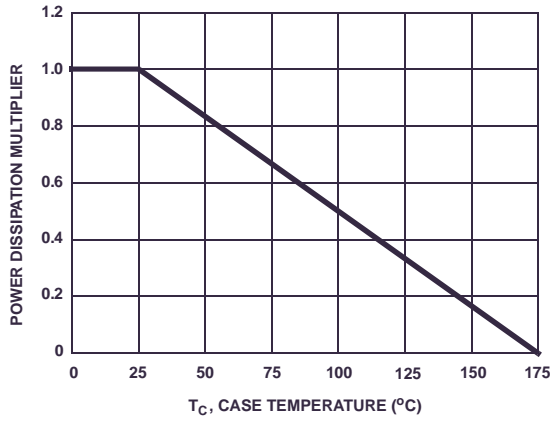


Figure 1. Normalized Power Dissipation vs Case Temperature

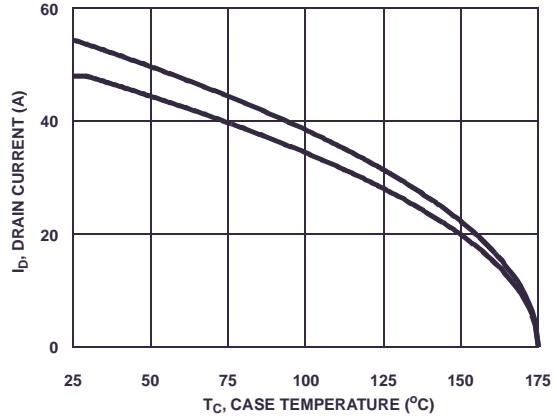


Figure 2. Maximum Continuous Drain Current vs Case Temperature

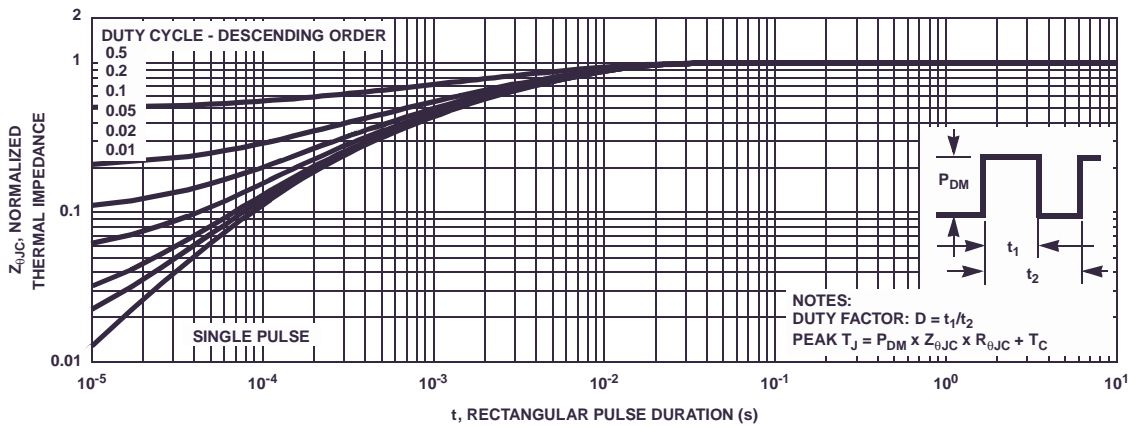


Figure 3. Normalized Maximum Transient Thermal Impedance

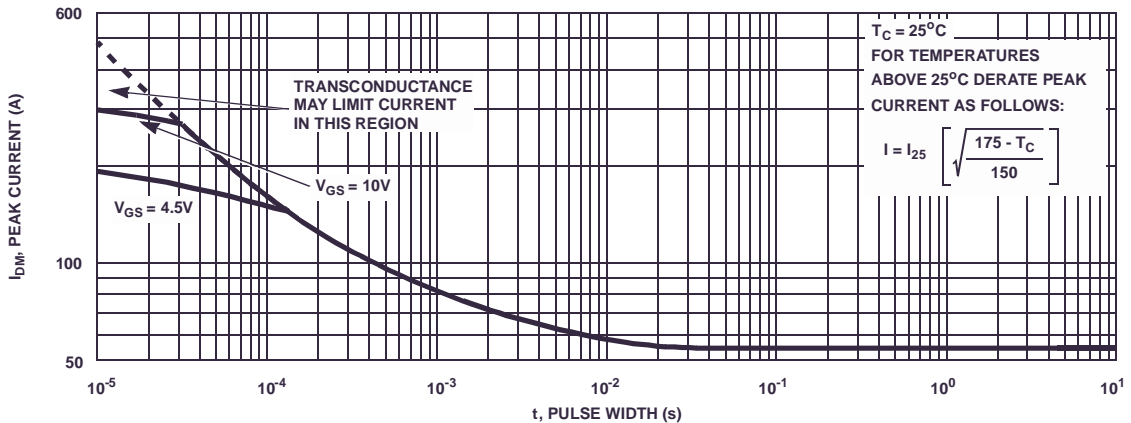


Figure 4. Peak Current Capability

Typical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

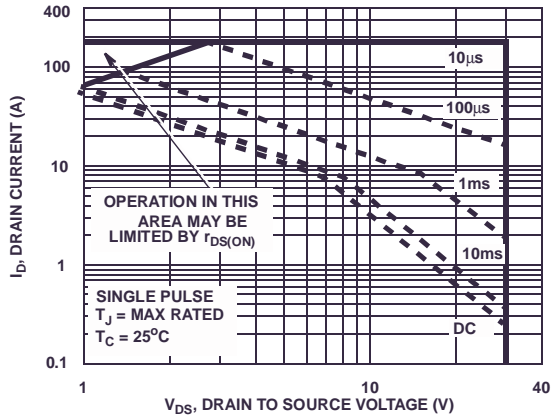
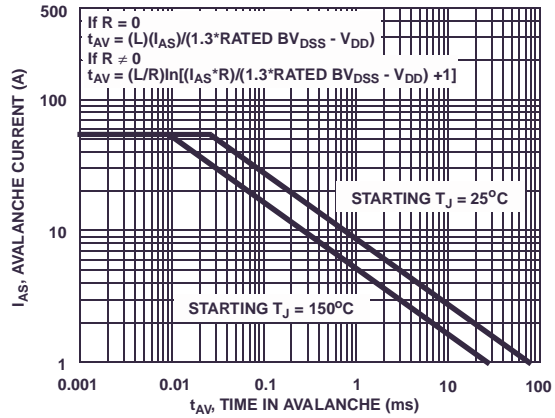


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to Fairchild Application Notes AN7514 and AN7515
Figure 6. Unclamped Inductive Switching Capability

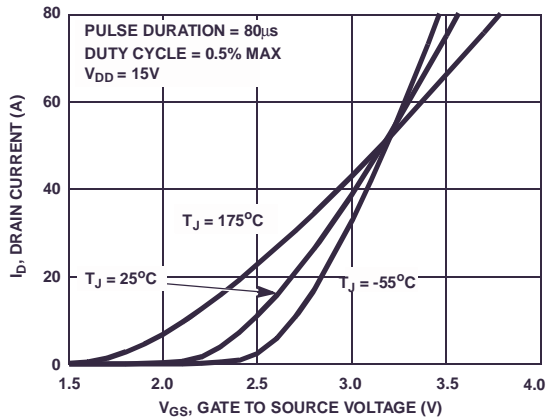


Figure 7. Transfer Characteristics

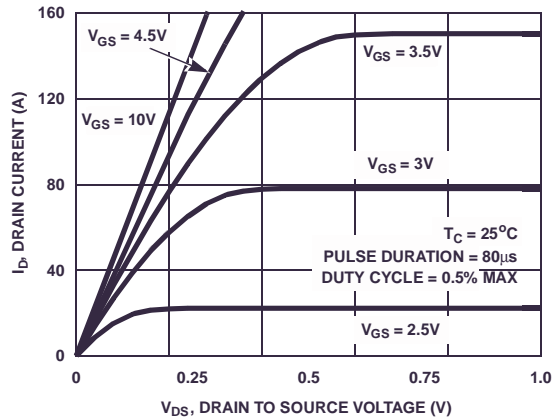


Figure 8. Saturation Characteristics

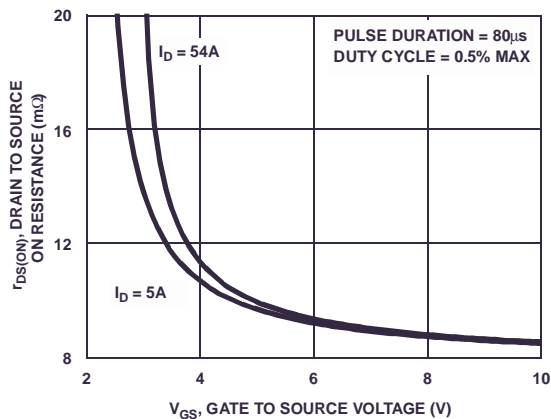


Figure 9. Drain to Source On Resistance vs Gate Voltage and Drain Current

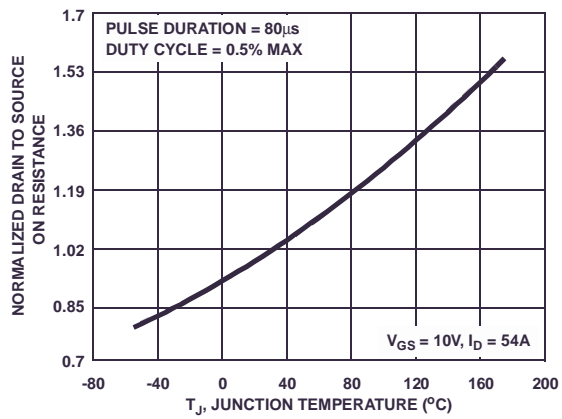


Figure 10. Normalized Drain to Source On Resistance vs Junction Temperature

Typical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted

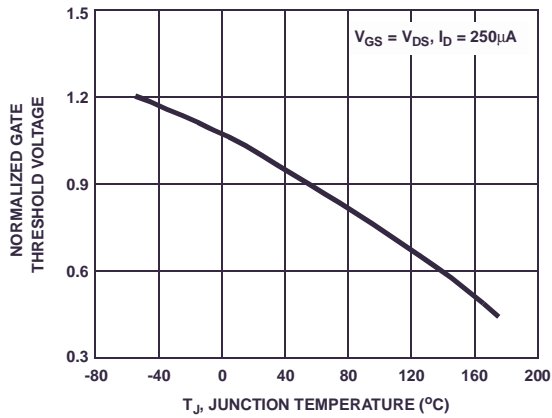


Figure 11. Normalized Gate Threshold Voltage vs Junction Temperature

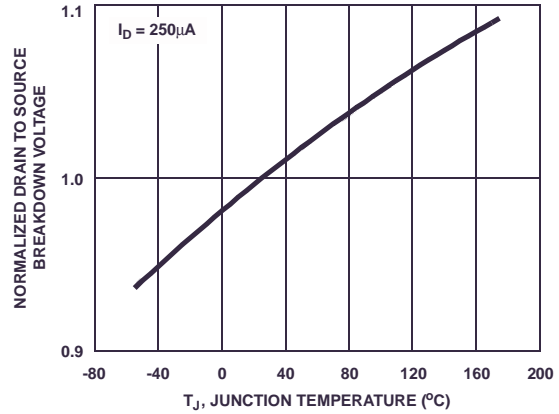


Figure 12. Normalized Drain to Source Breakdown Voltage vs Junction Temperature

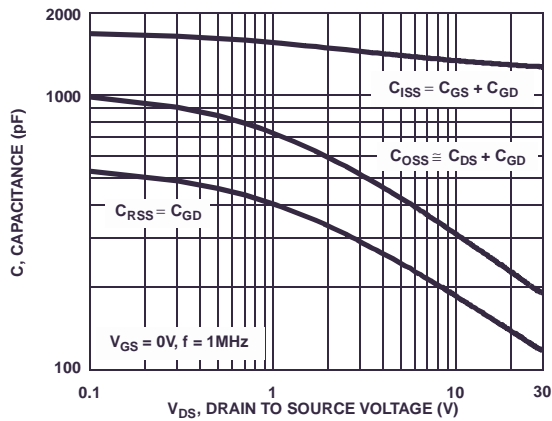


Figure 13. Capacitance vs Drain to Source Voltage

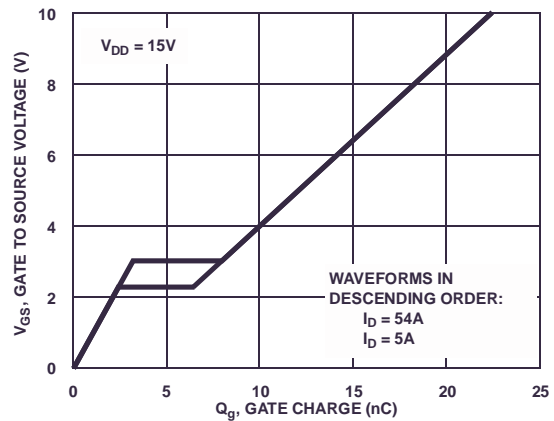


Figure 14. Gate Charge Waveforms for Constant Gate Current

Test Circuits and Waveforms

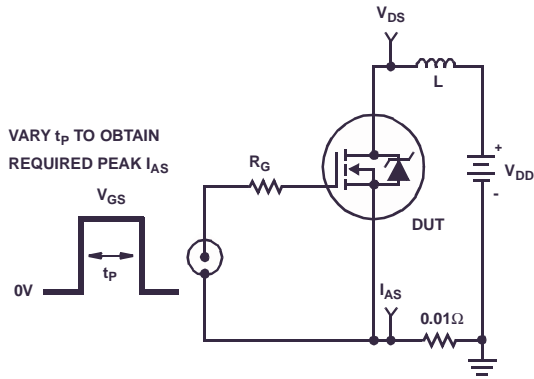


Figure 15. Unclamped Energy Test Circuit

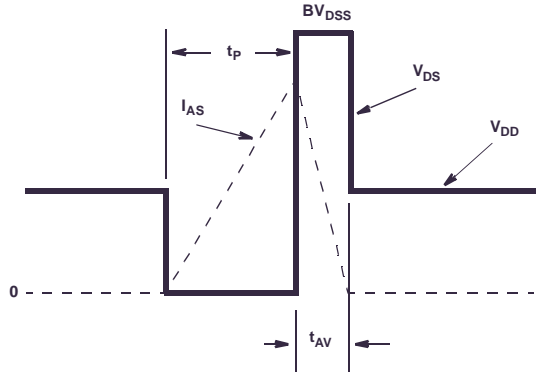


Figure 16. Unclamped Energy Waveforms

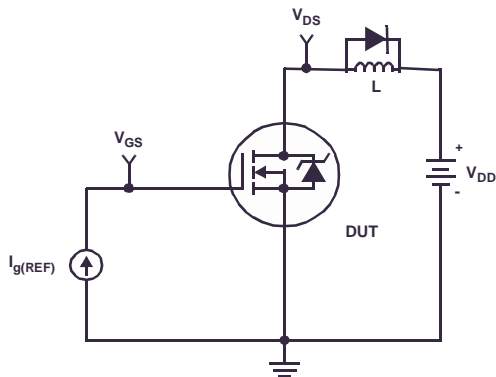


Figure 17. Gate Charge Test Circuit

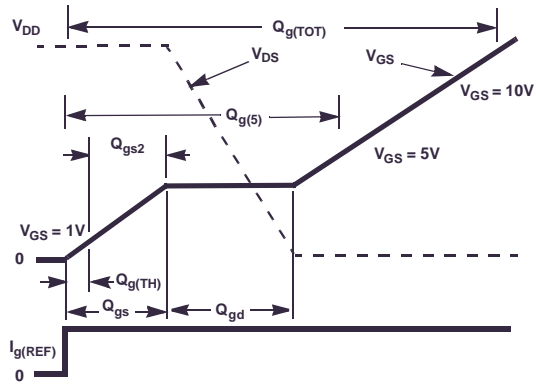


Figure 18. Gate Charge Waveforms

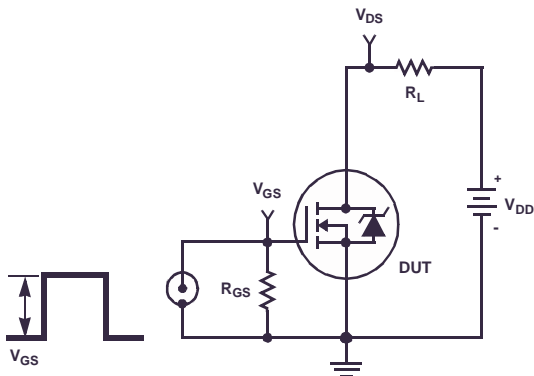


Figure 19. Switching Time Test Circuit

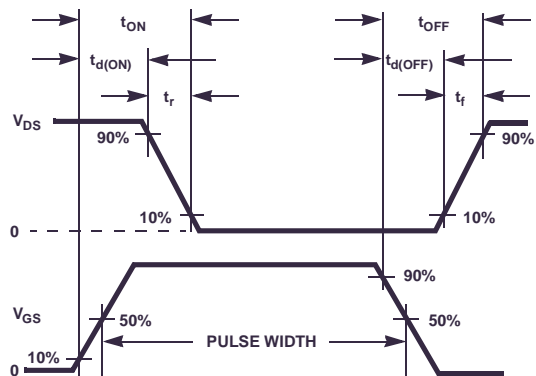


Figure 20. Switching Time Waveforms

PSPICE Electrical Model

.SUBCKT FDP8880 2 1 3 ; rev October 2004

Ca 12 8 9.5e-10
Cb 15 14 9.5e-10
Cin 6 8 1.15e-9

Dbody 7 5 DbodyMOD
Dbreak 5 11 DbreakMOD
Dplcap 10 5 DplcapMOD

Ebreak 11 7 17 18 32.88
Eds 14 8 5 8 1
Egs 13 8 6 8 1
Esg 6 10 6 8 1
Evtbres 6 21 19 8 1
Evttemp 20 6 18 22 1

It 8 17 1

Lgate 1 9 5.3e-9
Ldrain 2 5 1.0e-9
Lsource 3 7 1.7e-9

RLgate 1 9 53
RLdrain 2 5 10
RLsource 3 7 17

Mmed 16 6 8 8 MmedMOD
Mstro 16 6 8 8 MstroMOD
Mweak 16 21 8 8 MweakMOD

Rbreak 17 18 RbreakMOD 1
Rdrain 50 16 RdrainMOD 1.0e-3
Rgate 9 20 2.2
RSLC1 5 51 RSLCMOD 1e-6
RSLC2 5 50 1e3
Rsource 8 7 RsourceMOD 6.8e-3
Rvthres 22 8 RvthresMOD 1
Rvtemp 18 19 RvtempMOD 1
S1a 6 12 13 8 S1AMOD
S1b 13 12 13 8 S1BMOD
S2a 6 15 14 13 S2AMOD
S2b 13 15 14 13 S2BMOD

Vbat 22 19 DC 1

ESLC 51 50 VALUE={{(V(5,51)/ABS(V(5,51)))*(PWR(V(5,51)/(1e-6*170),5))}}

.MODEL DbodyMOD D (IS=3E-12 IKF=10 N=1.01 RS=5e-3 TRS1=8e-4 TRS2=2e-7
+ CJO=4.8e-10 M=0.55 TT=1e-11 XTI=2)

.MODEL DbreakMOD D (RS=0.2 TRS1=1e-3 TRS2=-8.8e-6)

.MODEL DplcapMOD D (CJO=5.5e-10 IS=1e-30 N=10 M=0.45)

.MODEL MstroMOD NMOS (VTO=2.10 KP=170 IS=1e-30 N=10 TOX=1 L=1u W=1u)

.MODEL MmedMOD NMOS (VTO=1.75 KP=10 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=2.2)

.MODEL MweakMOD NMOS (VTO=1.39 KP=0.05 IS=1e-30 N=10 TOX=1 L=1u W=1u RG=22 RS=0.1)

.MODEL RbreakMOD RES (TC1=8.0e-4 TC2=-8e-7)

.MODEL RdrainMOD RES (TC1=-12e-3 TC2=-.35e-4)

.MODEL RSLCMOD RES (TC1=9e-4 TC2=1e-6)

.MODEL RsourceMOD RES (TC1=5e-3 TC2=1e-6)

.MODEL RvtempMOD RES (TC1=-2.78e-3 TC2=1.5e-6)

.MODEL RvthresMOD RES (TC1=-1e-3 TC2=-8.2e-6)

.MODEL S1AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-4 VOFF=-3.5)

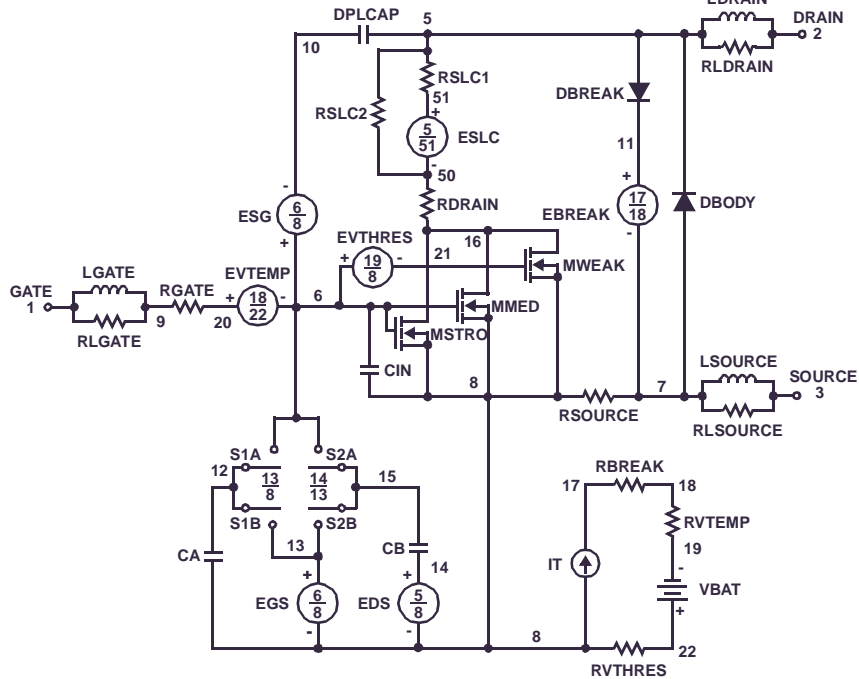
.MODEL S1BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-3.5 VOFF=-4)

.MODEL S2AMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-1.3 VOFF=-0.8)

.MODEL S2BMOD VSWITCH (RON=1e-5 ROFF=0.1 VON=-0.8 VOFF=-1.3)

.ENDS

Note: For further discussion of the PSPICE model, consult **A New PSPICE Sub-Circuit for the Power MOSFET Featuring Global Temperature Options**; IEEE Power Electronics Specialist Conference Records, 1991, written by William J. Hepp and C. Frank Wheatley.



SABER Electrical Model

rev October 2004

template FDP8880 n2,n1,n3

electrical n2,n1,n3

{

var i iscl

dp..model dbodymod = (isl=3e-12,ikf=10,nl=1.01,rs=5e-3,trs1=8e-4,trs2=2e-7,cjo=4.8e-10,m=0.55,tt=1e-11,xti=2)

dp..model dbreakmod = (rs=0.2,trs1=1e-3,trs2=-8.8e-6)

dp..model dplcapmod = (cjo=5.5e-10,isl=10e-30,nl=10,m=0.45)

m..model mstrongmod = (type=_n,vto=2.10,kp=170,rs=1e-30,tox=1)

m..model mmedmod = (type=_n,vto=1.75,kp=10,rs=1e-30,tox=1)

m..model mweakmod = (type=_n,vto=1.39,kp=0.05,rs=1e-30,tox=1,rs=0.1)

sw_vcsp..model s1amod = (ron=1e-5,roff=0.1,von=-4,voff=-3.5)

sw_vcsp..model s1bmod = (ron=1e-5,roff=0.1,von=-3.5,voff=-4)

sw_vcsp..model s2amod = (ron=1e-5,roff=0.1,von=-1.3,voff=-0.8)

sw_vcsp..model s2bmod = (ron=1e-5,roff=0.1,von=-0.8,voff=-1.3)

c.ca n12 n8 = 9.5e-10

c.cb n15 n14 = 9.5e-10

c.cin n6 n8 = 1.15e-9

dp.dbody n7 n5 = model=dbodymod

dp.dbreak n5 n11 = model=dbreakmod

dp.dplcap n10 n5 = model=dplcapmod

spe.ebreak n11 n7 n17 n18 = 32.88

spe.eds n14 n8 n5 n8 = 1

spe.egs n13 n8 n6 n8 = 1

spe.esg n6 n10 n6 n8 = 1

spe.evthres n6 n21 n19 n8 = 1

spe.evtemp n20 n6 n18 n22 = 1

i.it n8 n17 = 1

l.lgate n1 n9 = 5.3e-9

l.ldrain n2 n5 = 1.0e-9

l.lsource n3 n7 = 1.7e-9

res.rlgate n1 n9 = 53

res.rldrain n2 n5 = 10

res.rlsource n3 n7 = 17

m.mmed n16 n6 n8 n8 = model=mmedmod, l=1u, w=1u

m.mstrong n16 n6 n8 n8 = model=mstrongmod, l=1u, w=1u

m.mweak n16 n21 n8 n8 = model=mweakmod, l=1u, w=1u

res.rbreak n17 n18 = 1, tc1=8.0e-4,tc2=-8e-7

res.rdrain n50 n16 = 1.0e-3, tc1=-12e-3,tc2=.35e-4

res.rgate n9 n20 = 2.2

res.rslc1 n5 n51 = 1e-6, tc1=9e-4,tc2=1e-6

res.rslc2 n5 n50 = 1e3

res.rsource n8 n7 = 6.8e-3, tc1=5e-3,tc2=1e-6

res.rvthres n22 n8 = 1, tc1=-1e-3,tc2=-8.2e-6

res.rvtemp n18 n19 = 1, tc1=-2.78e-3,tc2=1.5e-6

sw_vcsp.s1a n6 n12 n13 n8 = model=s1amod

sw_vcsp.s1b n13 n12 n13 n8 = model=s1bmod

sw_vcsp.s2a n6 n15 n14 n13 = model=s2amod

sw_vcsp.s2b n13 n15 n14 n13 = model=s2bmod

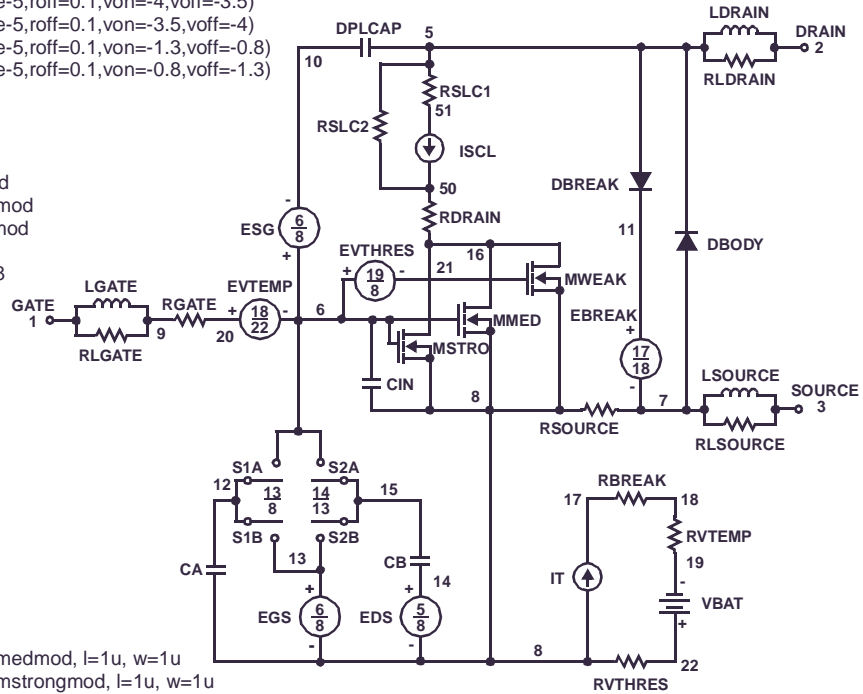
v.vbat n22 n19 = dc=1

equations {

i (n51->n50) += iscl

iscl: v(n51,n50) = ((v(n5,n51)/(1e-9+abs(v(n5,n51))))*((abs(v(n5,n51)*1e6/170)** 5)))

}



PSPICE Thermal Model

REV 23 December 2003

FDP8880T

CTHERM1 TH 6 8e-4
 CTHERM2 6 5 1e-3
 CTHERM3 5 4 2.5e-3
 CTHERM4 4 3 2.6e-3
 CTHERM5 3 2 8e-3
 CTHERM6 2 TL 1.5e-2

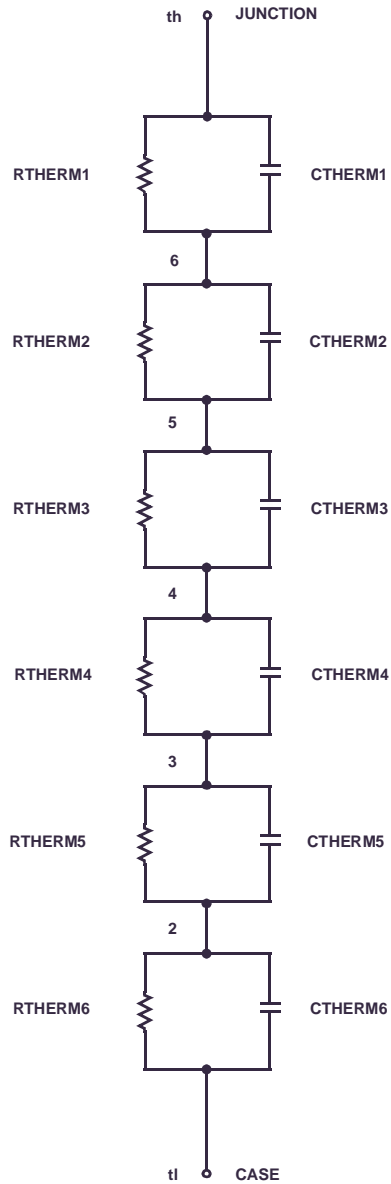
RTHERM1 TH 6 1.44e-1
 RTHERM2 6 5 1.9e-1
 RTHERM3 5 4 3.0e-1
 RTHERM4 4 3 4.0e-1
 RTHERM5 3 2 5.7e-1
 RTHERM6 2 TL 5.8e-1

SABER Thermal Model

SABER thermal model FDP8880T
 template thermal_model th tl
 thermal_c th, tl

```
{
ctherm.ctherm1 th 6 =8e-4
ctherm.ctherm2 6 5 =1e-3
ctherm.ctherm3 5 4 =2.5e-3
ctherm.ctherm4 4 3 =2.6e-3
ctherm.ctherm5 3 2 =8e-3
ctherm.ctherm6 2 tl =1.5e-2
```

```
rtherm.rtherm1 th 6 =1.44e-1
rtherm.rtherm2 6 5 =1.9e-1
rtherm.rtherm3 5 4 =3.0e-1
rtherm.rtherm4 4 3 =4.0e-1
rtherm.rtherm5 3 2 =5.7e-1
rtherm.rtherm6 2 tl =5.8e-1
}
```



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| ActiveArray™ | FAST® | IntelliMAX™ | Power247™ | SuperFET™ |
| Bottomless™ | FASTr™ | ISOPLANAR™ | PowerEdge™ | SuperSOT™-3 |
| CoolFET™ | FPST™ | LittleFET™ | PowerSaver™ | SuperSOT™-6 |
| CROSSVOLT™ | FRFET™ | MICROCOUPLER™ | PowerTrench® | SuperSOT™-8 |
| DOME™ | GlobalOptoisolator™ | MicroFET™ | QFET® | SyncFET™ |
| EcoSPARK™ | GTO™ | MicroPak™ | QS™ | TinyLogic® |
| E ² C MOS™ | HiSeC™ | MICROWIRE™ | QT Optoelectronics™ | TINYOPTO™ |
| EnSigna™ | I ² C™ | MSX™ | Quiet Series™ | TruTranslation™ |
| FACT™ | i-Lo™ | MSXPro™ | RapidConfigure™ | UHC™ |
| | | OCX™ | RapidConnect™ | UltraFET® |
| Across the board. Around the world.™ | | OCXPro™ | µSerDes™ | UniFET™ |
| The Power Franchise® | | OPTOLOGIC® | SILENT SWITCHER® | VCX™ |
| Programmable Active Droop™ | | OPTOPLANAR™ | SMART START™ | |
| | | PACMAN™ | SPM™ | |

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2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness.

PRODUCT STATUS DEFINITIONS

Definition of Terms

| Datasheet Identification | Product Status | Definition |
|--------------------------|------------------------|---|
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